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FAIRCHILD

SEMICONDUCTOR®

May 2007

74VHC157
Quad 2-Input Multiplexer

Features

■ High Speed: t_{PD} = 4.1ns (Typ.) at V_{CC} = 5V

■ Low power dissipation: I_{CC} = 4µA (Max.) at T_A = 25°C

■ High noise immunity: $V_{NIH} = V_{NIL}$ = 28% V_{CC} (Min.)

■ Power down protection is provided on all inputs

■ Low noise: V_{OLP} = 0.8V (Max.)

■ Pin and function compatible with 74HC157

General Description

The VHC157 is an advanced high speed CMOS Quad 2-Channel Multiplexer fabricated with silicon gate CMOS technology. It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

It consists of four 2-input digital multiplexers with common select and enable inputs. When the $\overline{\text{ENABLE}}$ input is held "H" level, selection of data is inhibited and all the outputs become "L" level. The SELECT decoding determines whether the I_{0x} or I_{1x} inputs get routed to their corresponding outputs.

An Input protection circuit ensures that 0V to 7V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5V to 3V systems and on two supply systems such as battery back up. This circuit prevents device destruction due to mismatched supply and input voltages.

Ordering Information

Order Number	Package Number	Package Description
74VHC157M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VHC157SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHC157MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering number.

Connection Diagram
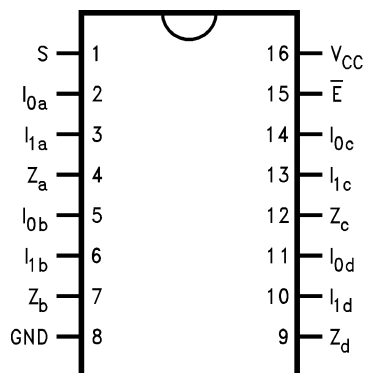
Pin Description

Pin Names	Description
I_{0a}–I_{0d}	Source 0 Data Inputs
I_{1a}–I_{1d}	Source 1 Data Inputs
$\overline{E}$	Enable Input
S	Select Input
Z_a–Z_d	Outputs

Logic Symbols

IEEE/IEC

Functional Description

The VHC157 is a quad 2-input multiplexer. It selects four bits of data from two sources under the control of a common Select inp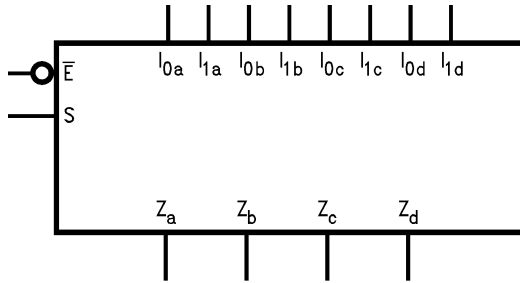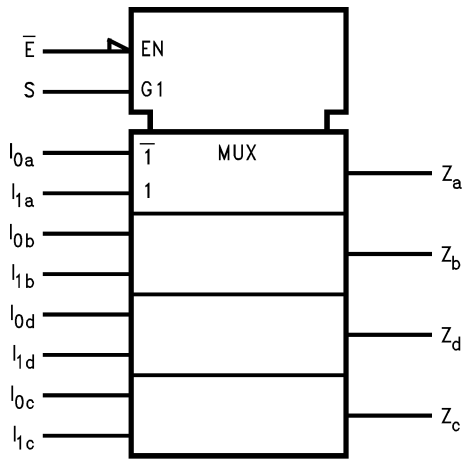ut (S). The Enable input ($\overline{E}$) is active-LOW. When $\overline{E}$ is HIGH, all of the outputs (Z) are forced LOW regardless of all other inputs. The VHC157 is the logic implementation of a 4-pole, 2-position switch where the position of the switch is determined by the logic levels supplied to the Select input. The logic equations for the outputs are shown below:

$$Z_a = \overline{E} \cdot (I_{1a} \cdot S + I_{0a} \cdot \overline{S})$$
$$Z_b = \overline{E} \cdot (I_{1b} \cdot S + I_{0b} \cdot \overline{S})$$
$$Z_c = \overline{E} \cdot (I_{1c} \cdot S + I_{0c} \cdot \overline{S})$$
$$Z_d = \overline{E} \cdot (I_{1d} \cdot S + I_{0d} \cdot \overline{S})$$

A common use of the VHC157 is the moving of data from two groups of registers to four common output busses. The particular register from which the data comes is determined by the state of the Select input. A less obvious use is as a function generator. The VHC157 can generate any four of the sixteen different functions of two variables with one variable common. This is useful for implementing gating functions.

Truth Table

Inputs				Outputs
$\overline{E}$	S	I_0	I_1	Z
H	X	X	X	L
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Logic Diagram

I_{0a} I_{1a} I_{0b} I_{1b} I_{0c} I_{1c} I_{0d} I_{1d} $\overline{E}$ S

Z_a Z_b Z_c Z_d
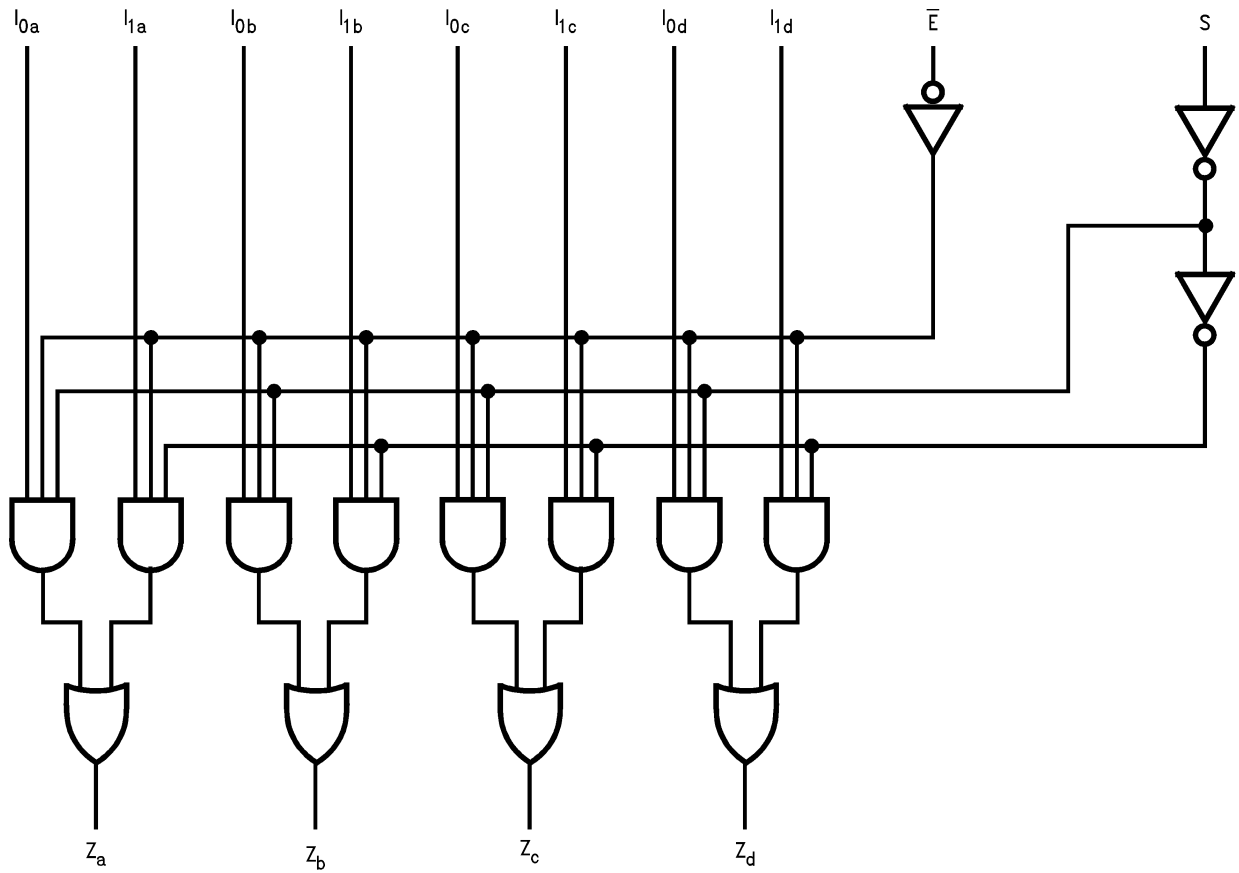
Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

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Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	–0.5V to +7.0V
V_{IN}	DC Input Voltage	–0.5V to +7.0V
V_{OUT}	DC Output Voltage	–0.5V to V_{CC} + 0.5V
I_{IK}	Input Diode Current	–20mA
I_{OK}	Output Diode Current	±20mA
I_{OUT}	DC Output Current	±25mA
I_{CC}	DC V_{CC} / GND Current	±50mA
T_{STG}	Storage Temperature	–65°C to +150°C
T_L	Lead Temperature (Soldering, 10 seconds)	260°C

Recommended Operating Conditions[1]

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	2.0V to +5.5V
V_{IN}	Input Voltage	0V to +5.5V
V_{OUT}	Output Voltage	0V to V_{CC}
T_{OPR}	Operating Temperature	–40°C to +85°C
t_r, t_f	Input Rise and Fall Time,	
	V_{CC} = 3.3V ± 0.3V	0ns/V ~ 100ns/V
	V_{CC} = 5.0V ± 0.5V	0ns/V ~ 20ns/V

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

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DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions		T_A = 25°C			T_A = −40°C to +85°C		Units
					Min.	Typ.	Max.	Min.	Max.	
V_{IH}	HIGH Level Input Voltage	2.0			1.50			1.50		V
		3.0–5.5			0.7 x V_{CC}			0.7 x V_{CC}		
V_{IL}	LOW Level Input Voltage	2.0					0.50		0.50	V
		3.0–5.5					0.3 x V_{CC}		0.3 x V_{CC}	
V_{OH}	HIGH Level Output Voltage	2.0	$V_{IN} = V_{IH}$ or V_{IL}	I_{OH} = −50µA	1.9	2.0		1.9		V
		3.0			2.9	3.0		2.9		
		4.5			4.4	4.5		4.4		
		3.0		I_{OH} = −4mA	2.58			2.48		
		4.5		I_{OH} = −8mA	3.94			3.80		
V_{OL}	LOW Level Output Voltage	2.0	$V_{IN} = V_{IH}$ or V_{IL}	I_{OL} = 50µA		0.0	0.1		0.1	V
		3.0				0.0	0.1		0.1	
		4.5				0.0	0.1		0.1	
		3.0		I_{OL} = 4mA			0.36		0.44	
		4.5		I_{OL} = 8mA			0.36		0.44	
I_{IN}	Input Leakage Current	0–5.5	V_{IN} = 5.5V or GND				±0.1		±1.0	µA
I_{CC}	Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND				4.0		40.0	µA

Noise Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = 25°C		Units
				Typ.	Limits	
V_{OLP}[3]	Quiet Output Maximum Dynamic V_{OL}	5.0	C_L = 50pF	0.3	0.8	V
V_{OLV}[3]	Quiet Output Minimum Dynamic V_{OL}	5.0	C_L = 50pF	−0.3	−0.8	V
V_{IHD}[3]	Minimum HIGH Level Dynamic Input Voltage	5.0	C_L = 50pF		3.5	V
V_{ILD}[3]	Maximum LOW Level Dynamic Input Voltage	5.0	C_L = 50pF		1.5	V

Note:
2. Parameter guaranteed by design.

AC Electrical Characteristics

| Symbol	Parameter	V$_{CC}$ (V)	Conditions	T$_A$ = 25°C			T$_A$ = −40°C to +85°C		Units
				Min.	Typ.	Max.	Min.	Max.	
t$_{PLH}$, t$_{PHL}$	Propagation Delay, I$_n$ to Z$_n$	3.3 ± 0.3	C$_L$ = 15pF		6.2	9.7	1.0	11.5	ns
			C$_L$ = 50pF		8.7	13.2	1.0	15.0	
		5.0 ± 0.5	C$_L$ = 15pF		4.1	6.4	1.0	7.5	ns
			C$_L$ = 50pF		5.6	8.4	1.0	9.5	
t$_{PLH}$, t$_{PHL}$	Propagation Delay, S to Z$_n$	3.3 ± 0.3	C$_L$ = 15pF		8.4	13.2	1.0	15.5	ns
			C$_L$ = 50pF		10.9	16.7	1.0	19.0	
		5.0 ± 0.5	C$_L$ = 15pF		5.3	8.1	1.0	9.5	ns
			C$_L$ = 50pF		6.8	10.1	1.0	11.5	
t$_{PLH}$, t$_{PHL}$	Propagation Delay, $\overline{E}$ to Z$_n$	3.3 ± 0.3	C$_L$ = 15pF		8.7	13.6	1.0	16.0	ns
			C$_L$ = 50pF		11.2	17.1	1.0	19.5	
		5.0 ± 0.5	C$_L$ = 15pF		5.6	8.6	1.0	10.0	ns
			C$_L$ = 50pF		7.1	10.6	1.0	12.0	
C$_{IN}$	Input Capacitance		V$_{CC}$ = Open		4	10		10	pF
C$_{PD}$	Power Dissipation Capacitance		(3)		20				pF

Note:

3. C$_{PD}$ is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:

I_{CC} (opr.) = $C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}$

Physical Dimensions

Dimensions are in millimeters unless otherwise noted.

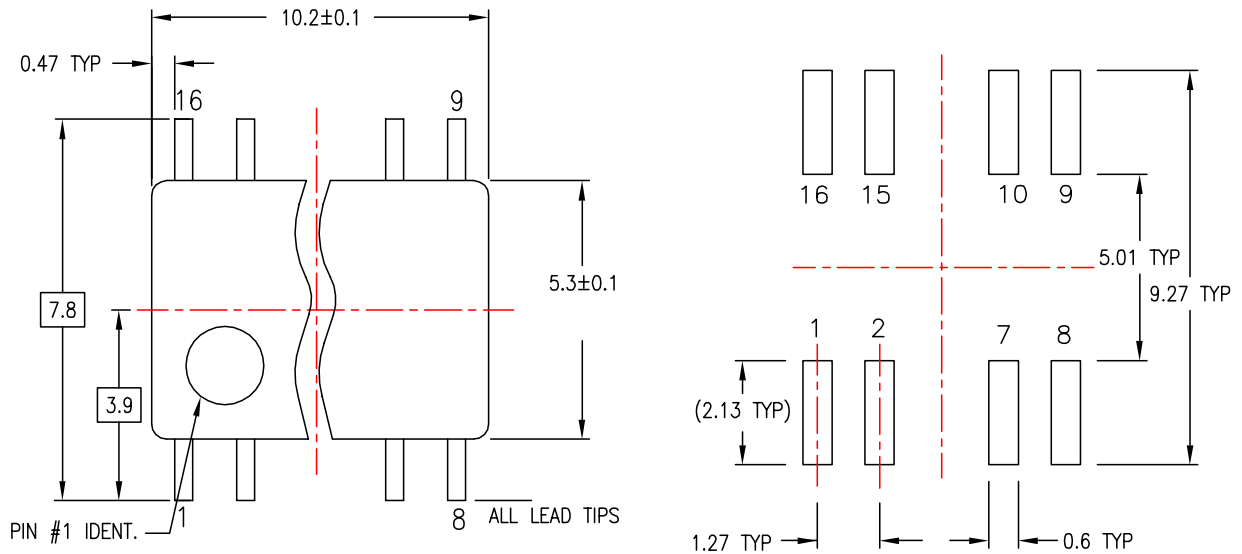LAND PATTERN RECOMMENDATION
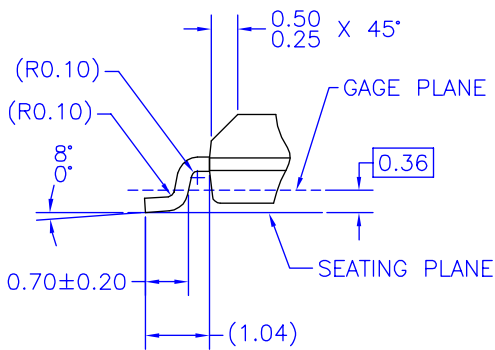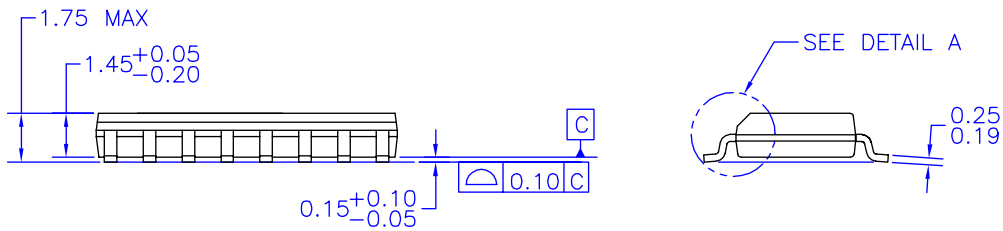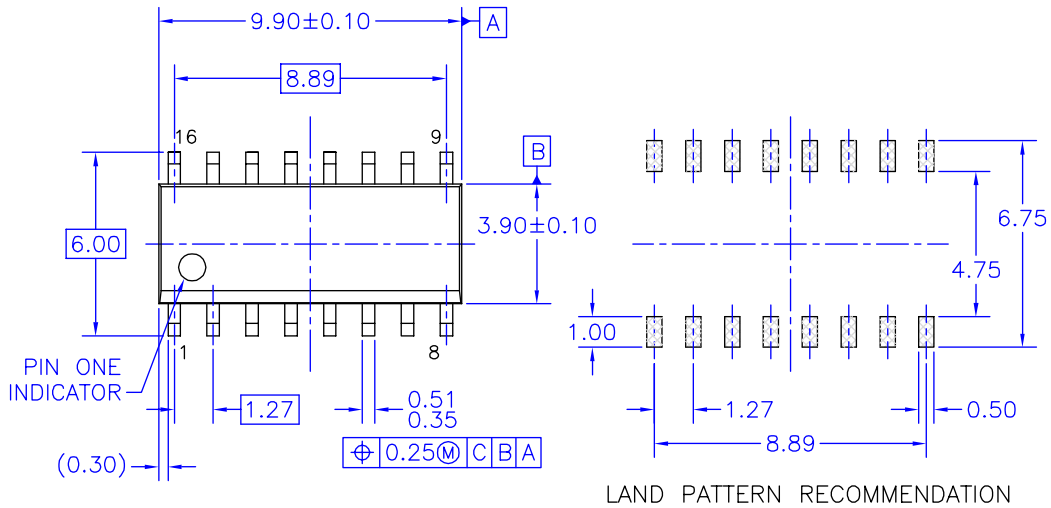
NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC
   MS–012, VARIATION AC, ISSUE C,
   DATED MAY 1990.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE MOLD
   FLASH OR BURRS.
D) STANDARD LEAD FINISH:
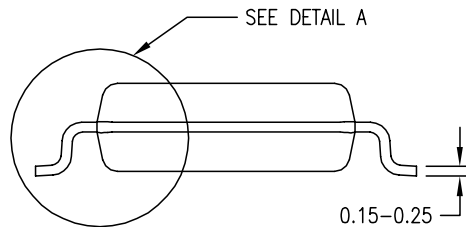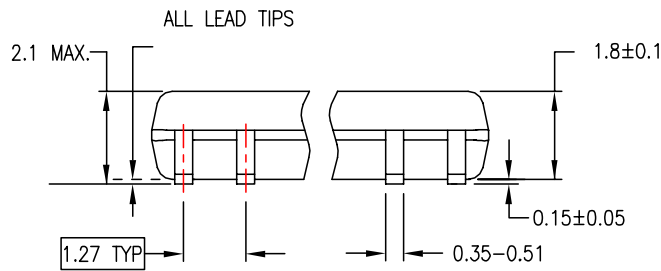   200 MICROINCHES / 5.08 MICRONS MIN.
   LEAD/TIN (SOLDER) ON COPPER.

DETAIL A
SCALE: 2:1

M16AREVK

Figure 1. 16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M16A

Physical Dimensions (Continued)
Dimensions are in millimeters unless otherwise noted.

10.2±0.1

0.47 TYP

16   9

7.8

3.9

5.3±0.1

PIN #1 IDENT. 1

8   ALL LEAD TIPS

16   15   10   9

5.01 TYP

9.27 TYP

(2.13 TYP)

1   2   7   8

1.27 TYP

0.6 TYP

LAND PATTERN RECOMMENDATION

ALL LEAD TIPS

2.1 MAX.

1.8±0.1

0.15±0.05

1.27 TYP

0.35−0.51

DIMENSIONS ARE IN MILLIMETERS

SEE DETAIL A

0.15−0.25

7° TYP

GAGE PLANE

0°−8° TYP

0.25

0.60±0.15

1.25

SEATING PLANE

DETAIL A

NOTES:
A. CONFORMS TO EIAJ EDR−7320 REGISTRATION,
   ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
   FLASH, AND TIE BAR EXTRUSIONS.
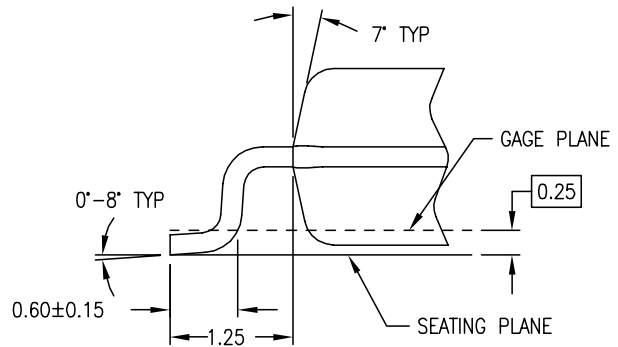
M16DREVC

**Figure 2. 16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D**

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Physical Dimensions (Continued)
Dimensions are in millimeters unless otherwise noted.

A

5.00±0.10

4.55

16   9

6.4

3.2

B

4.4±0.1

0.2 C B A
ALL LEAD TIPS

1   8

PIN #1 IDENT.

0.11

5.90

4.45   7.35

0.65

1.45

5.00

LAND PATTERN RECOMMENDATION (F)

ALL LEAD TIPS
0.1 C

1.1 MAX

(0.90)

-C-

0.65   0.19 – 0.30

0.10±0.05

0.10 M A B S C S

SEE DETAIL A

0.09-0.20

12° TOP AND BOTTOM

GAGE PLANE

0.25

0°-8°

0.6±0.1

SEATING PLANE

DETAIL A
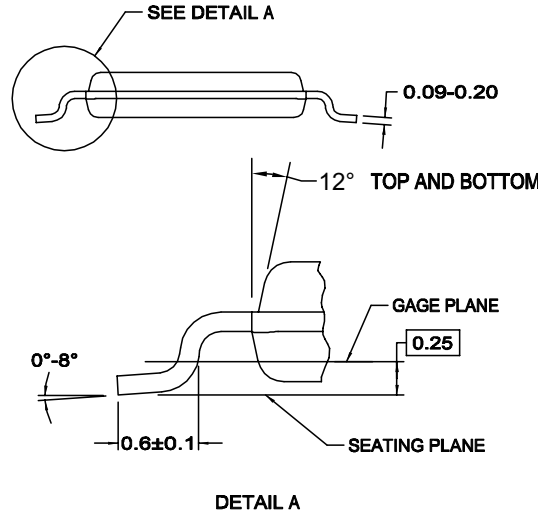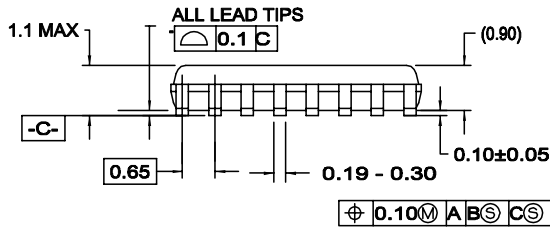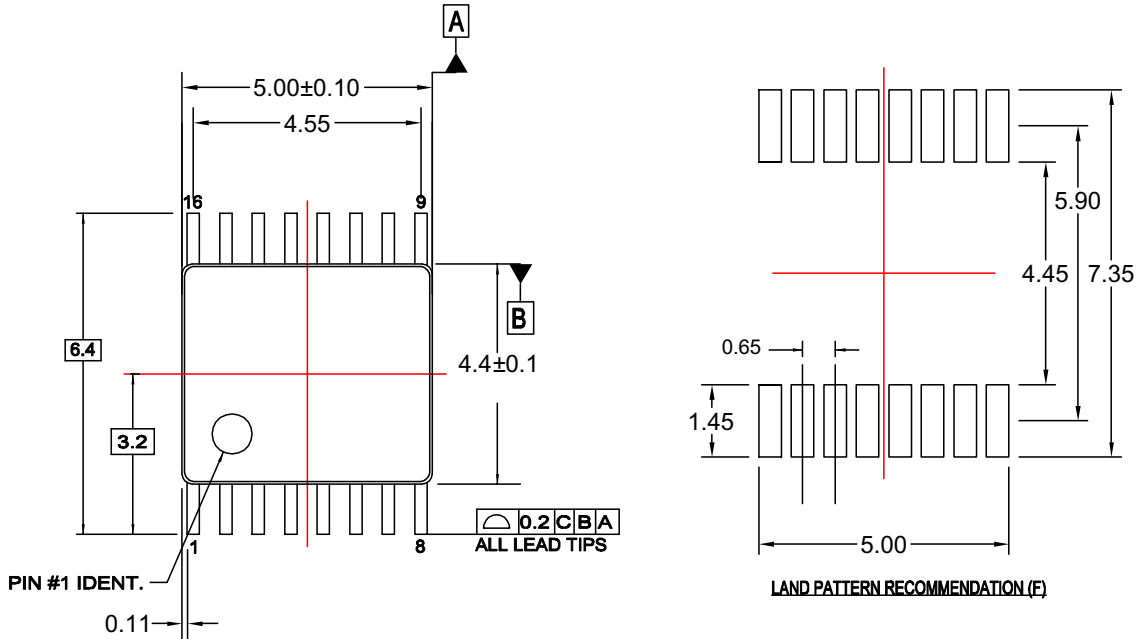
NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB.
B. DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH,
   AND TIE BAR EXTRUSIONS
D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1994
E. DRAWING FILE NAME: MTC16REV4
F. LAND PATTERN RECOMMENDATION PER IPC7351 - ID#
   TSOP65P640X110-16N

MTC16rev4

**Figure 3. 16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC16**

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2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

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PUBLICATION ORDERING INFORMATION

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